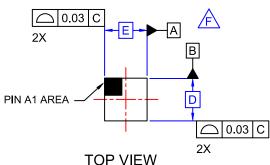
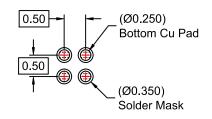
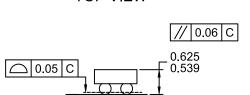
## WLCSP4 1x1x0.582 CASE 567PU ISSUE O

**DATE 31 OCT 2016** 

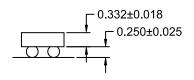




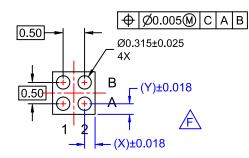


/b\

## RECOMMENDED LAND PATTERN (NSMD PAD TYPE)



## SIDE VIEWS



**SEATING PLANE** 

## NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

**BOTTOM VIEW** 

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DESCRIPTION:	WLCSP4 1x1x0.582		PAGE 1 OF 1

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